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Title: **CN1378685T: BONDING PAD OF SUSPENSION CIRCUIT**  
 Country: **CN China**  
 Kind: **T Publication of the translation of an International Application**  
 Inventor: **WANG XIAOMING; Hong Kong**  
**TAO FENG; Hong Kong**  
 Assignee: **XINKE INDUSTRY CO., LTD. Hong Kong**  
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 Published / Filed: **2002-11-06 / 2000-08-09**  
 Application Number: **CN2000000814030**  
 IPC Code: **G11B 5/53; G11B 5/49; G11B 5/48;**  
 ECLA Code: **None**  
 Priority Number: **2000-08-09 WO2000000000227**  
 INPADOC Legal Status: **None** [Get Now: Family Legal Status Report](#)  
 Designated Country: **CN**

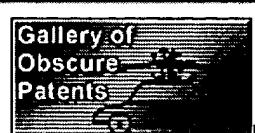
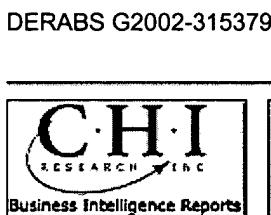


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PDF	Publication	Pub. Date	Filed	Title
<input type="checkbox"/>	<a href="#">WO200213189C1</a>	2002-03-14	2000-08-09	BONDING PAD OF SUSPENSION CIRCUIT
<input type="checkbox"/>	<a href="#">WO200213189A1</a>	2002-02-14	2000-08-09	BONDING PAD OF SUSPENSION CIRCUIT
<input type="checkbox"/>	<a href="#">US20030058577A1</a>	2003-03-27	2002-11-13	Bonding pad of suspension circuit
<input type="checkbox"/>	<a href="#">US20020030935A1</a>	2002-03-14	2000-12-18	Bonding pad of suspension circuit
<input checked="" type="checkbox"/>	<a href="#">CN1378685T</a>	2002-11-06	2000-08-09	BONDING PAD OF SUSPENSION CIRCUIT

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